



Material Content Data Sheet



Sales Product Name		BSZ123N08NS3 G		Issued		19. January 2018		
MA#		MA001599694						
Package		PG-TSDSON-8-2		Weight*		38.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	4.73	4.73	47338	47338
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54	
	non noble metal	zinc	7440-66-6	0.008	0.02		216	
	non noble metal	iron	7439-89-6	0.168	0.43		4325	
wire	non noble metal	copper	7440-50-8	6.808	17.56	18.02	175633	180228
	non noble metal	copper	7440-50-8	0.041	0.11	0.11	1066	1066
	encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		868
	plastics	epoxy resin	-	1.733	4.47		44718	
	inorganic material	silicondioxide	60676-86-0	15.061	38.87	43.43	388573	434159
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9988	9988
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24834	24834
solder	non noble metal	tin	7440-31-5	0.037	0.10		950	
	noble metal	silver	7440-22-4	0.046	0.12		1187	
	non noble metal	lead	7439-92-1	1.758	4.53	4.75	45345	47482
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		111	
	non noble metal	iron	7439-89-6	0.086	0.22		2225	
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	9.03	9.26	90327	92691
	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		195	
	non noble metal	iron	7439-89-6	0.151	0.39		3893	
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158077	162214
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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